

WIFI Module (ISM43340-M4G-L44-10CF)

MB1486

Table of contents

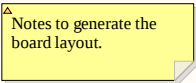
Sheet 1 : Project overview
Sheet 2 : WIFI_MODULE

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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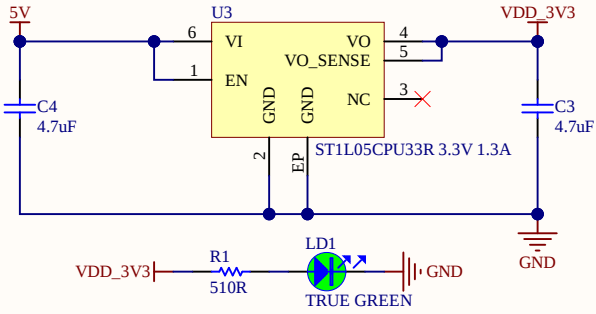
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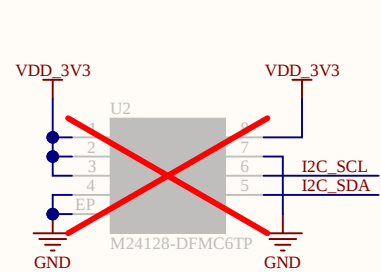
Title: Project overview	
Project: WIFI Module (ISM43340-M4G-L44-10CF)	
Variant: Soldered	
Revision: A-03	Reference: MB1486
Size: A4	Sheet: 1 of 2



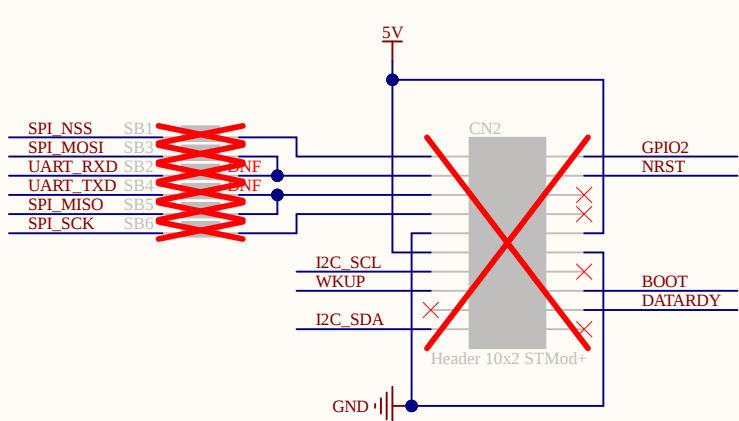
POWER



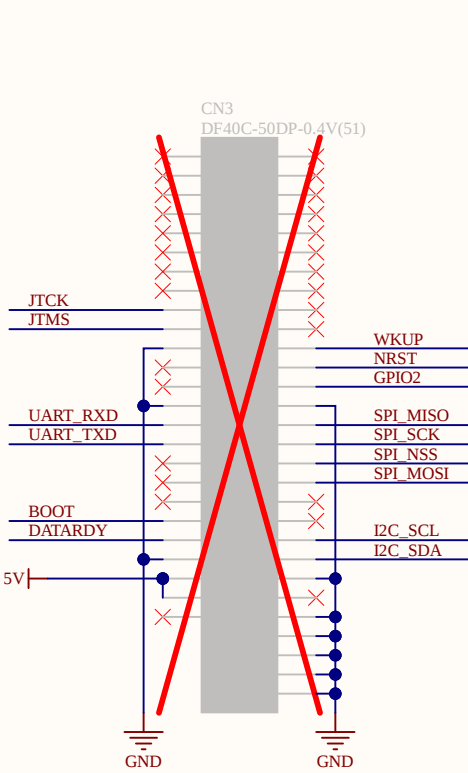
I2C Bus EEPROM



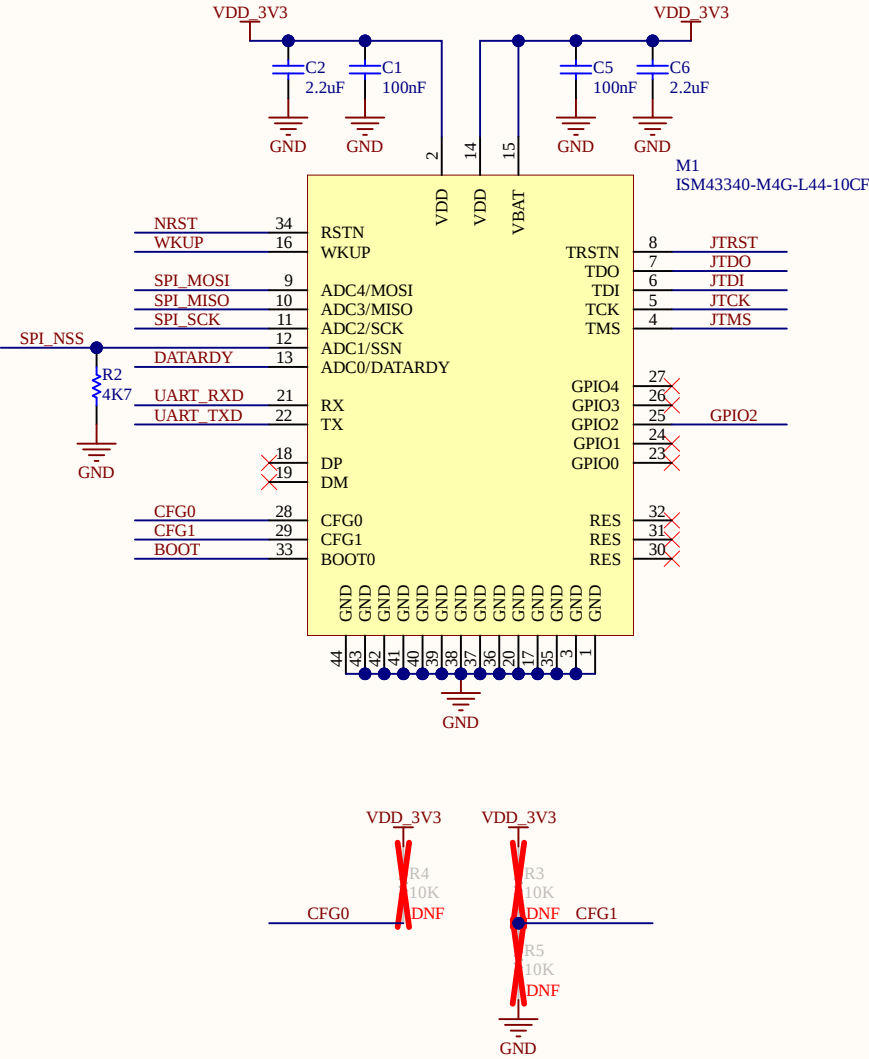
STMOD+



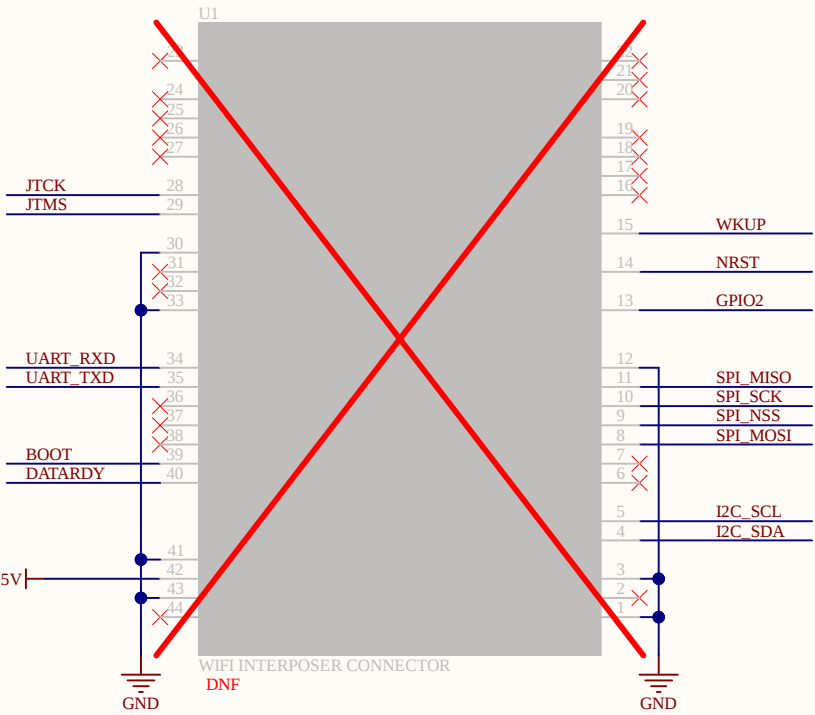
DF40C



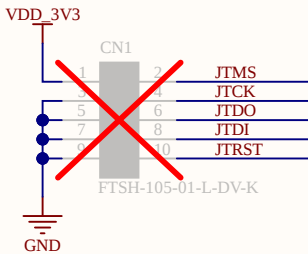
WIFI MODULE (ISM43340-M4G-L44-10CF)



INTERPOSER CONNECTOR

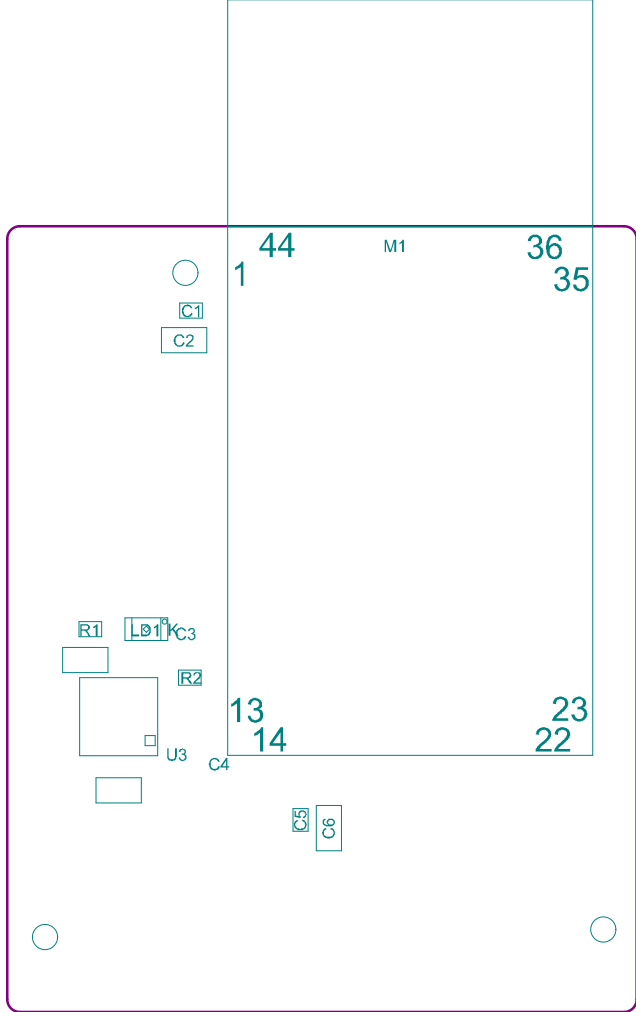


DEBUG

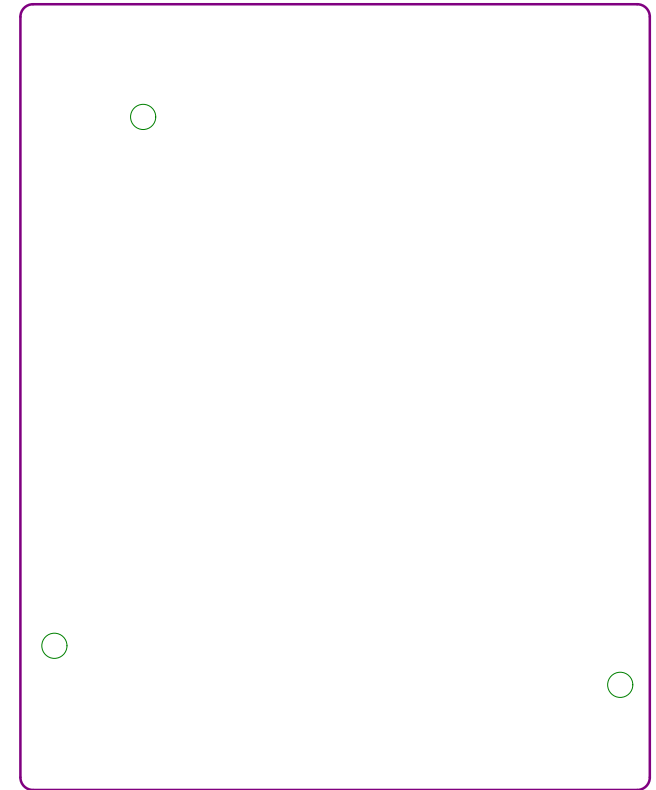
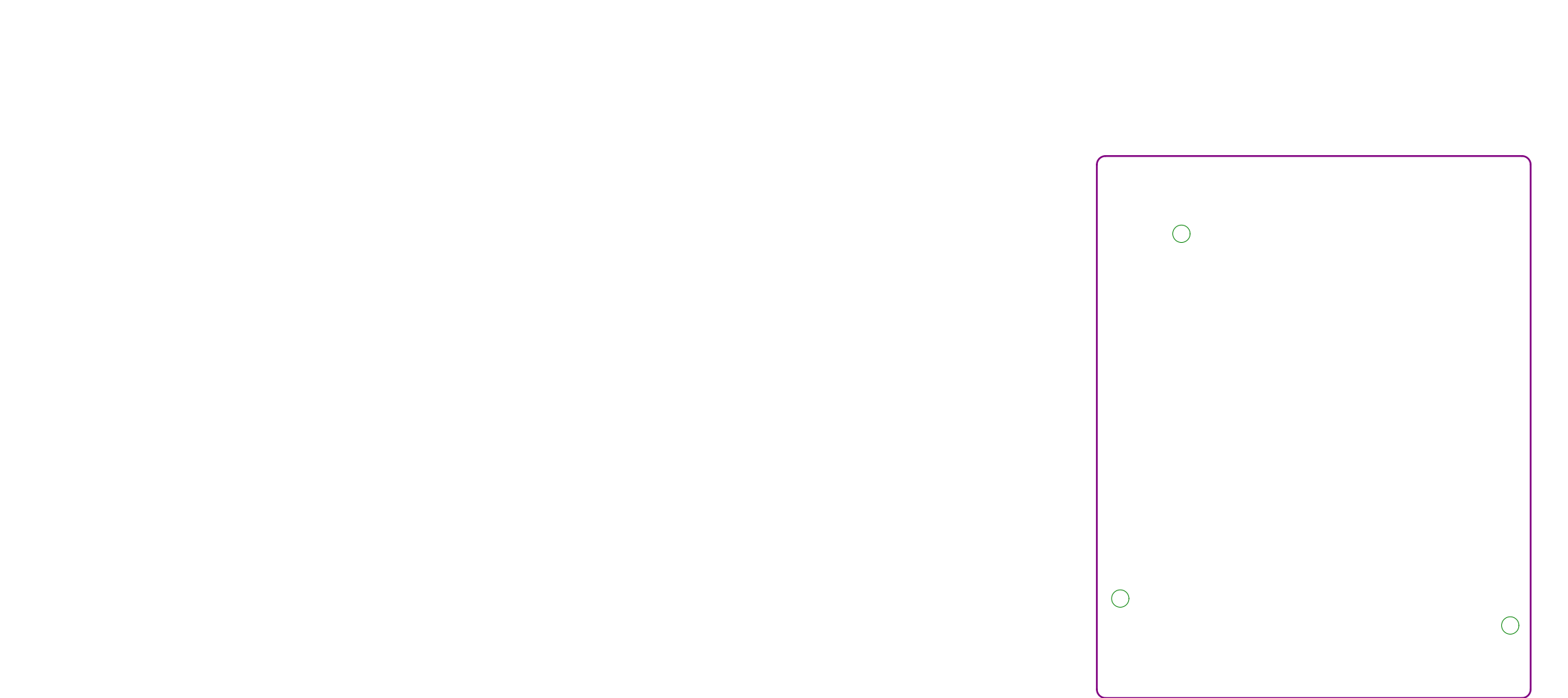


PCB & sticker

HW8	HW9
PCB	BOARD REF
mbxxxxY	mbxxxxy-zz syyywxxxxx



Project: WIFI Module (ISM43340-M4G-L44-10CF)		
Layer: M14-Top Assembly	Gerber: .GM14	
Variant: Soldered	Ref: MB1486	
Date: 18-APRIL-26	Rev: A	



Project: WIFI Module (ISM43340-M4G-L44-10CF)		
Layer: M15-Bottom Assembly	Gerber: .GM15	
Variant: Soldered	Ref: MB1486	
Date: 18-APRIL-26	Rev: A	

